

WAFER-INTERPOSER ASSEMBLY

ABSTRACT OF THE DISCLOSURE

A wafer-interposer assembly (10) includes a semiconductor wafer (12) having a plurality of semiconductor die (14) that have a plurality of first electrical contact pads (16). An interposer (22) is connected to the semiconductor wafer (12) such that a plurality of second electrical contact pads (26) associated with the interposer (22) are respectively connected to at least some of the first electrical contact pads (16) via conductive attachment elements (20). A communication interface (28) is integrally associated with the interposer (22) and electrically connected to at least some of the plurality of second electrical contact pads (26). The interposer (22) and the semiconductor wafer (12) are operable to be singulated into a plurality of chip assemblies.